



景碩科技股份有限公司
Kinsus Interconnect Technology Corp.

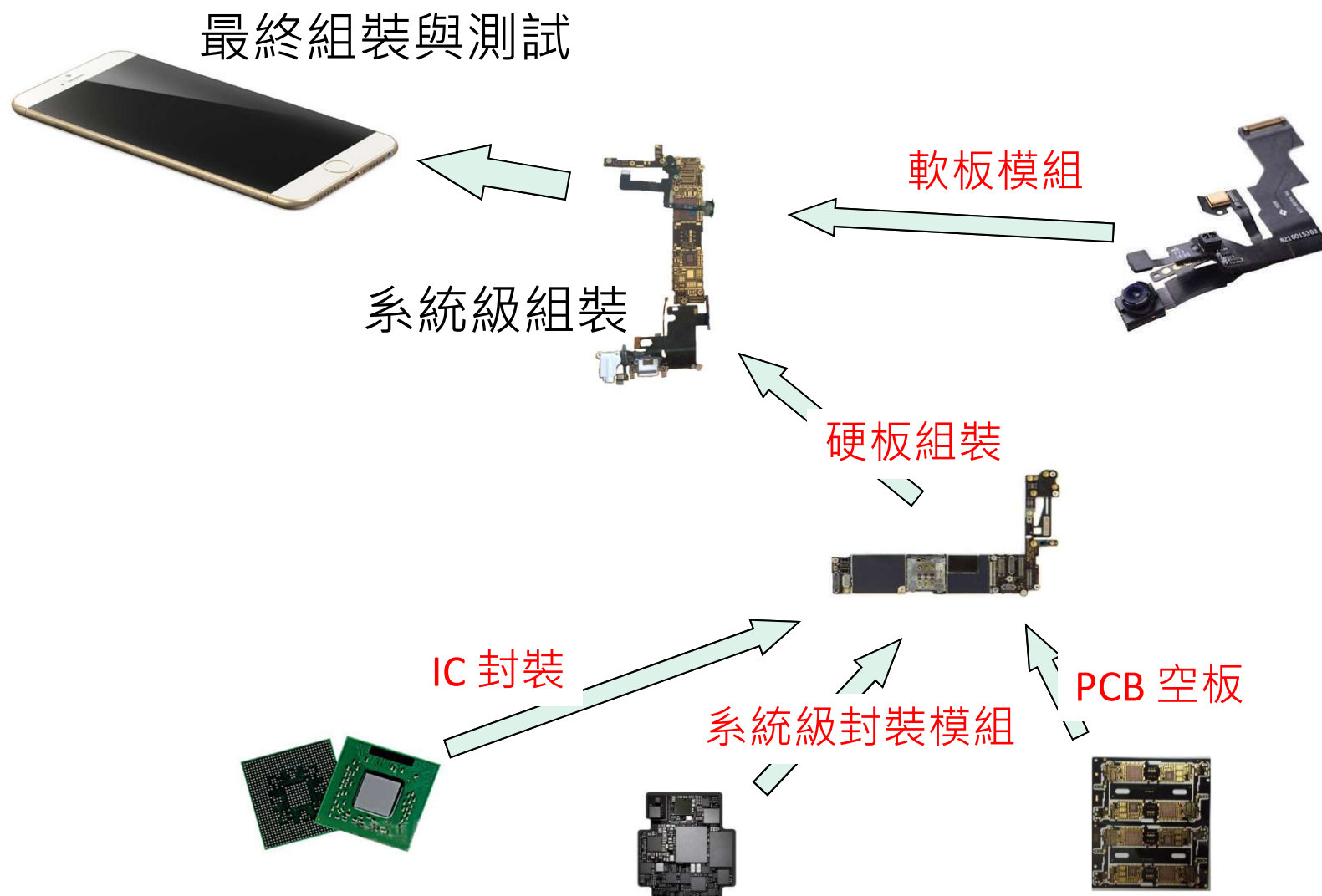
Dec 2022



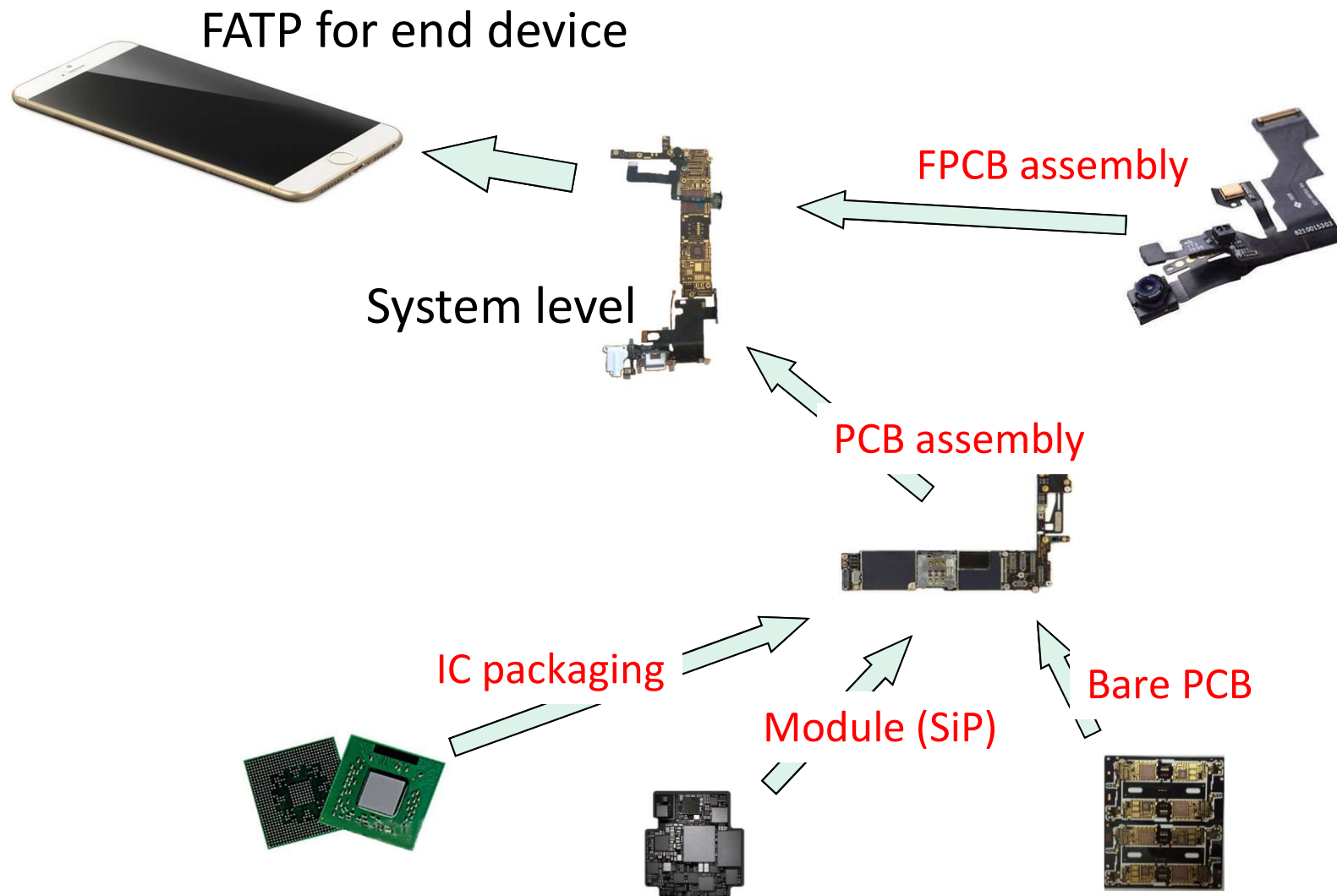
IC 封裝技術

IC Packaging Technology

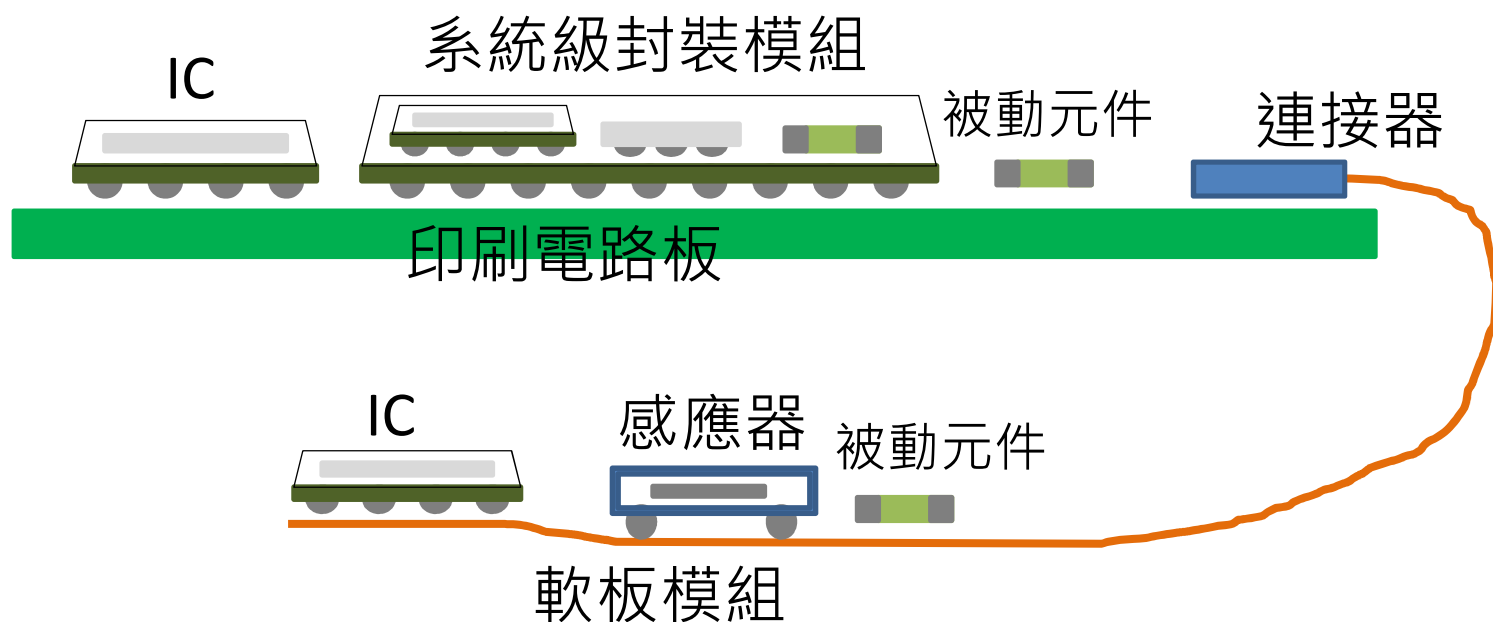
電子產品構裝的各個層次



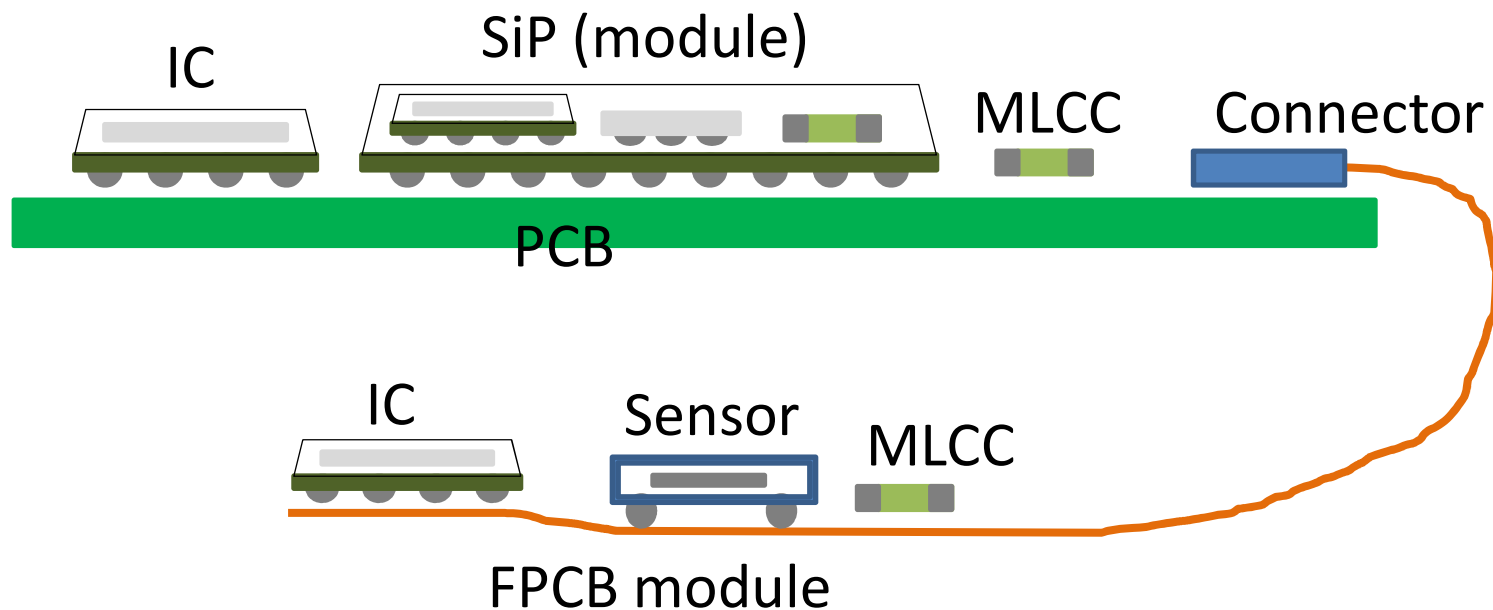
Levels of Assembly



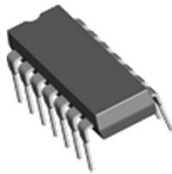
電子產品的組裝結構



Basic structure of electronic devices



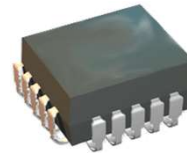
各種形式的IC 封裝



DIP



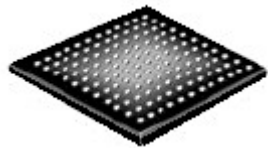
QFP



PLCC



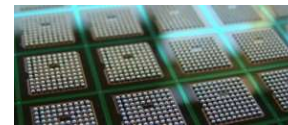
TSOP



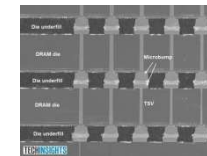
PBGA/
Flip-Chip BGA



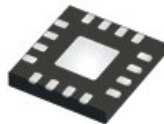
CSP



WLP



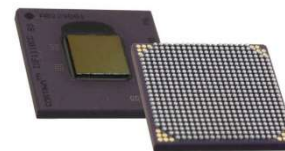
TSV



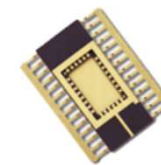
QFN



DFN



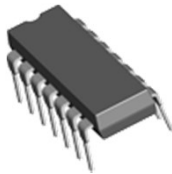
Ceramic BGA



Ceramic chip

市場規模: 2016 年2,520 億顆, 其中 719 億顆為 BGA 封裝

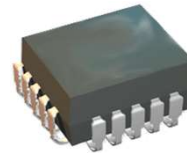
Different types of IC packaging



DIP



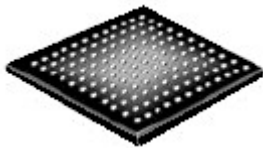
QFP



PLCC



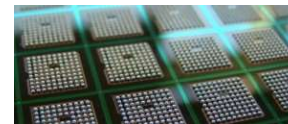
TSOP



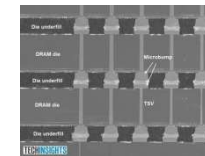
PBGA/
Flip-Chip BGA



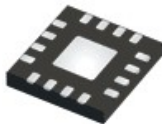
CSP



WLP



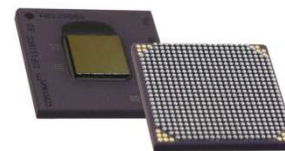
TSV



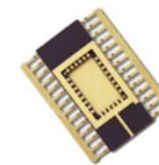
QFN



DFN

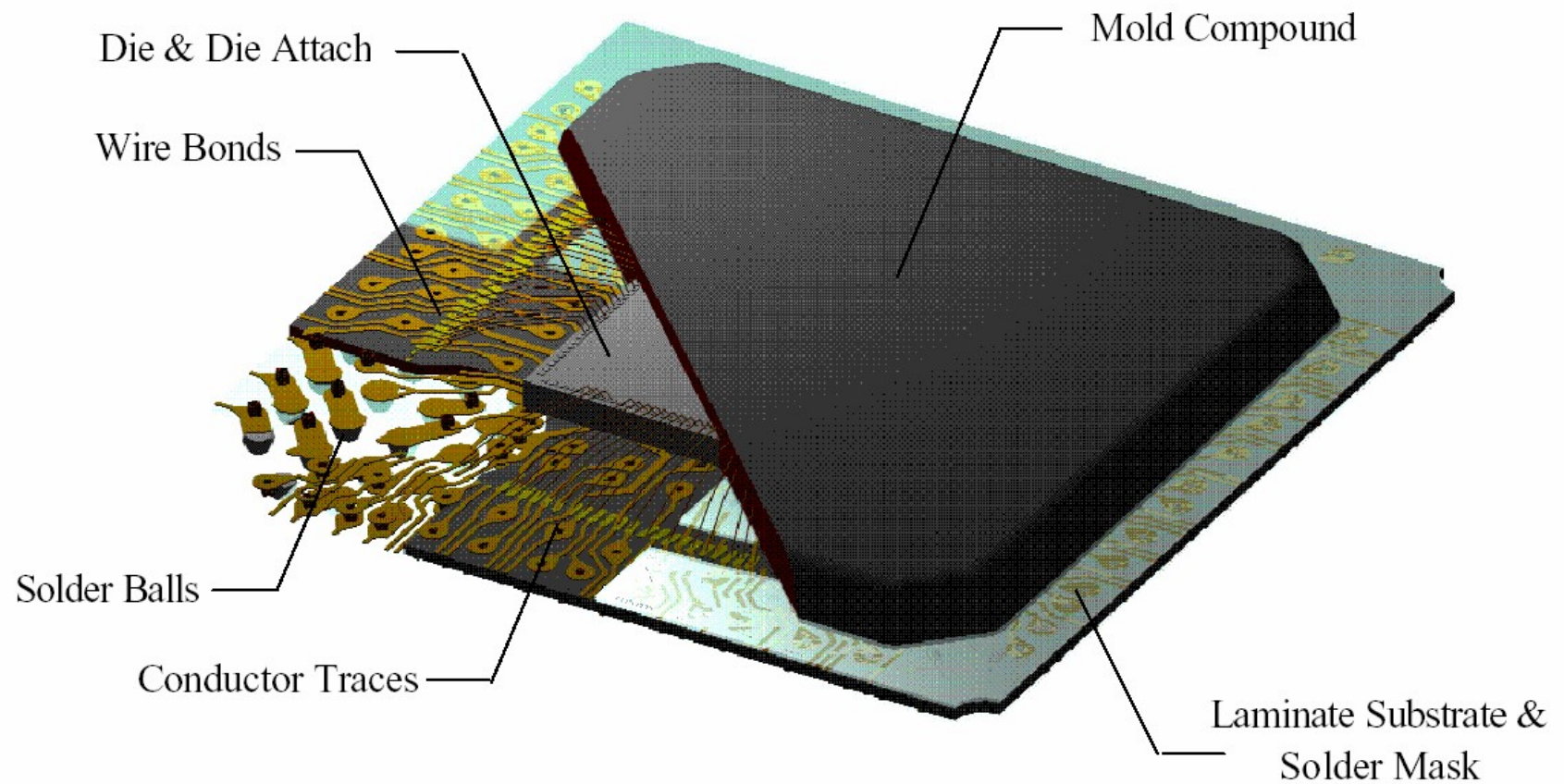


Ceramic BGA

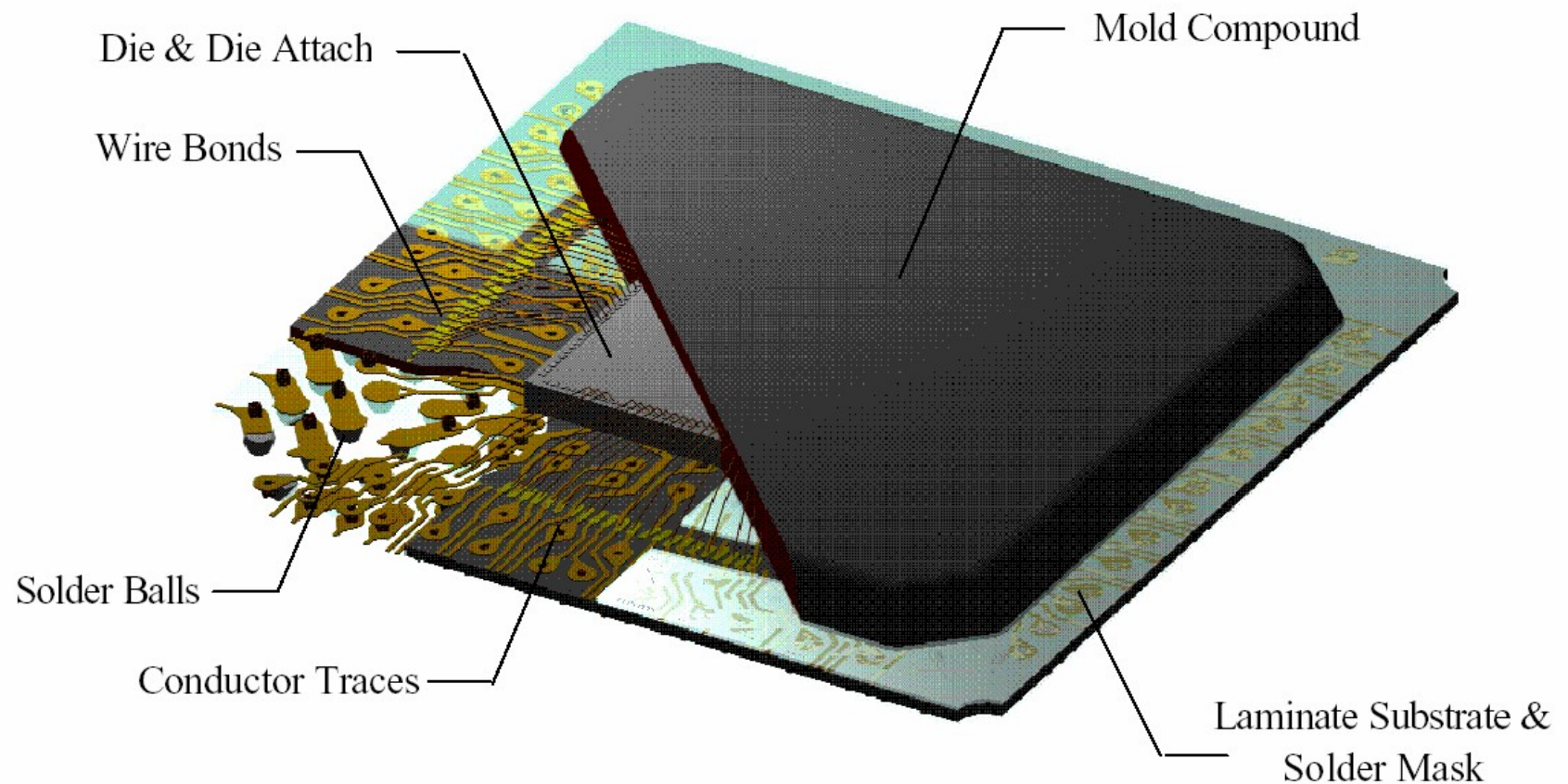


Ceramic chip

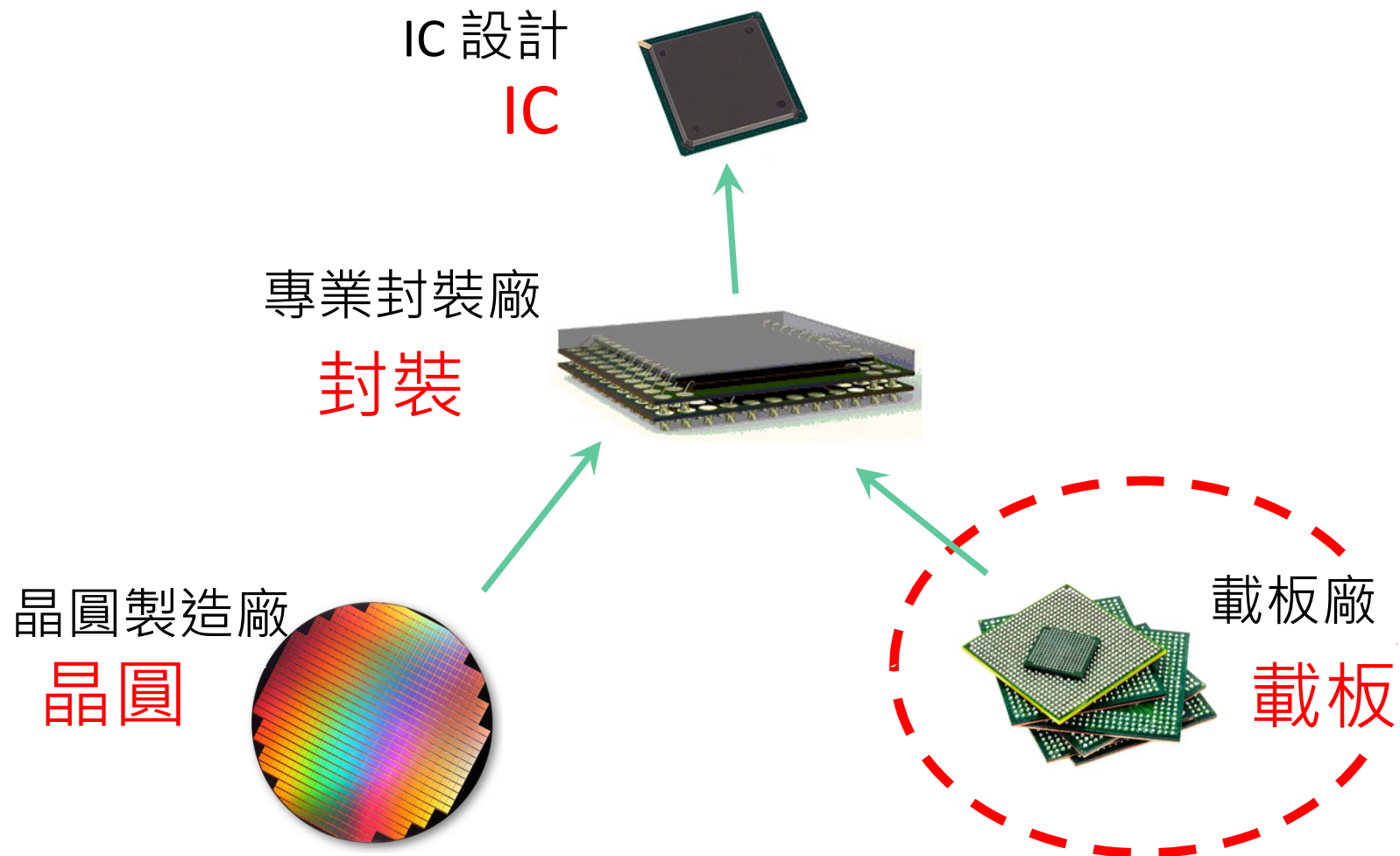
Market size : 252 Billion units in 2016, 71.9 Billion units in BGA substrates



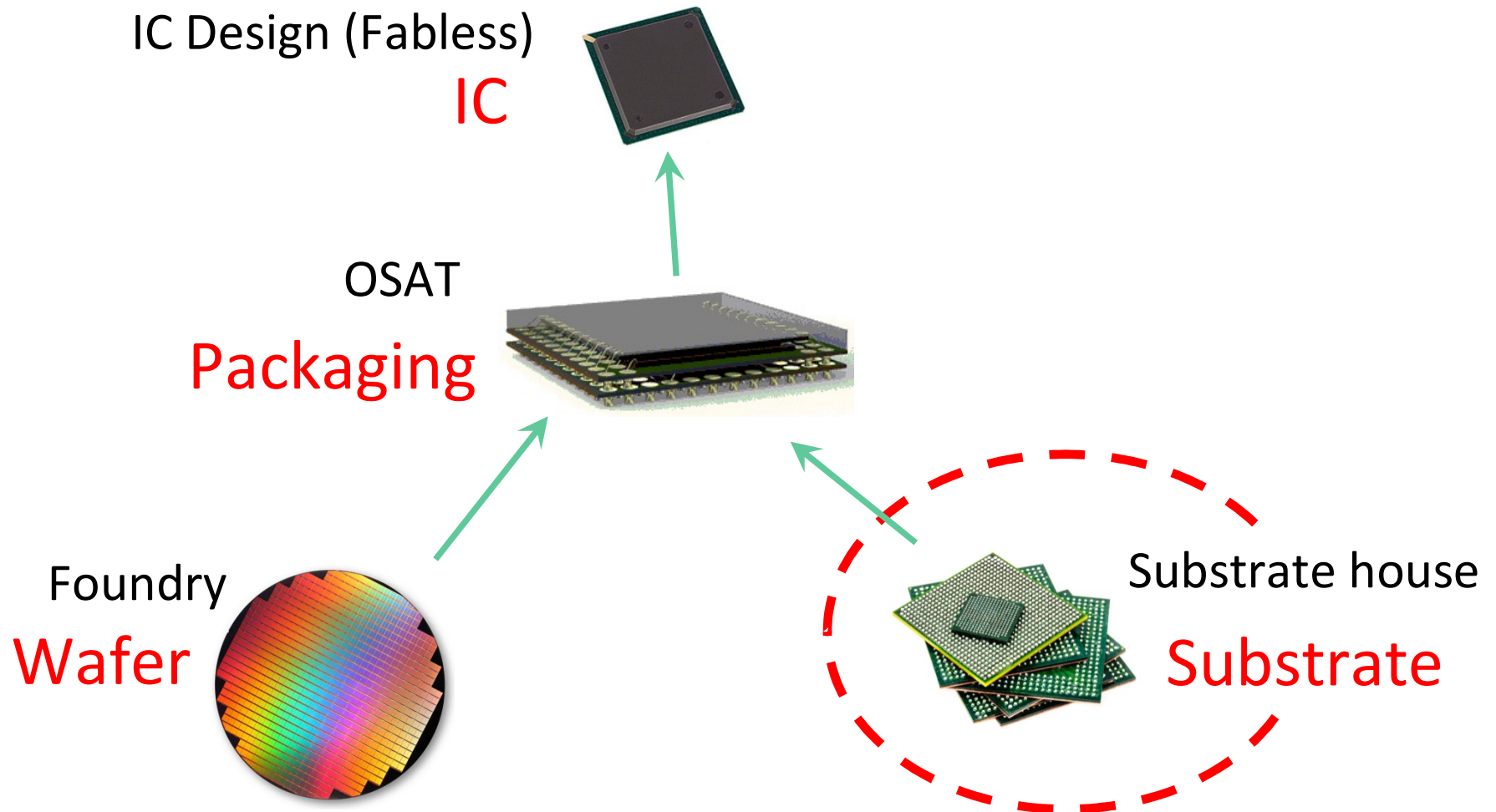
What Substrate Makers do?



IC 半導體上下游供應鏈關係



IC Manufacturing Supply Chain





About Kinsus

基本資料



- 公司成立 2000
台股上市掛牌 2004
- 資本額： 新台幣 45.08 億元
- 廠區： 總部
 IC 載板

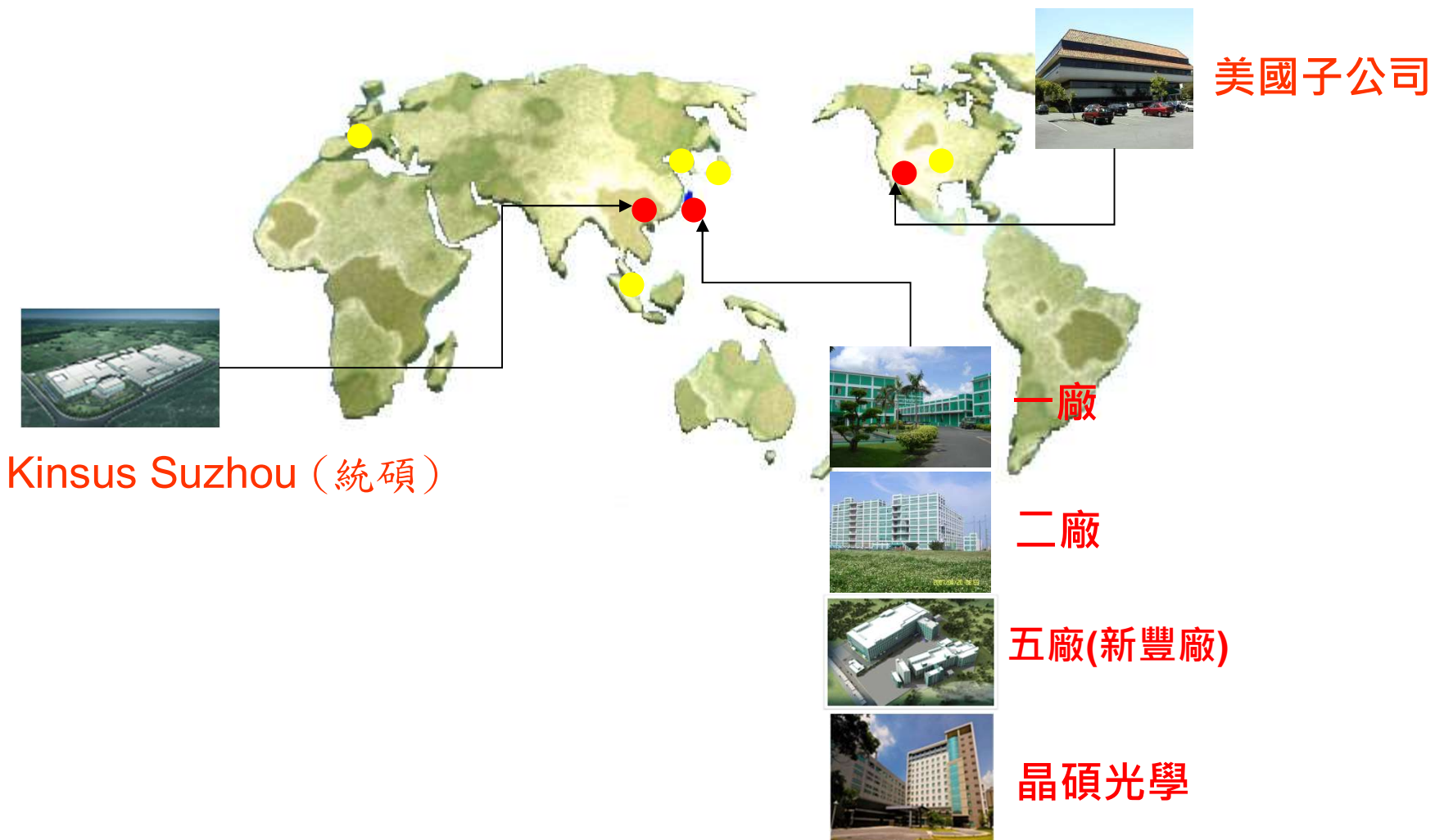
 Kinsus USA
 統碩科技
 晶碩光學
- 新屋 / 台灣
- 一廠 及 二廠
- 新豐廠 (五廠)
- Santa Clara / California
- 蘇州 / 中國
- 桃園 / 台灣

Basic Information

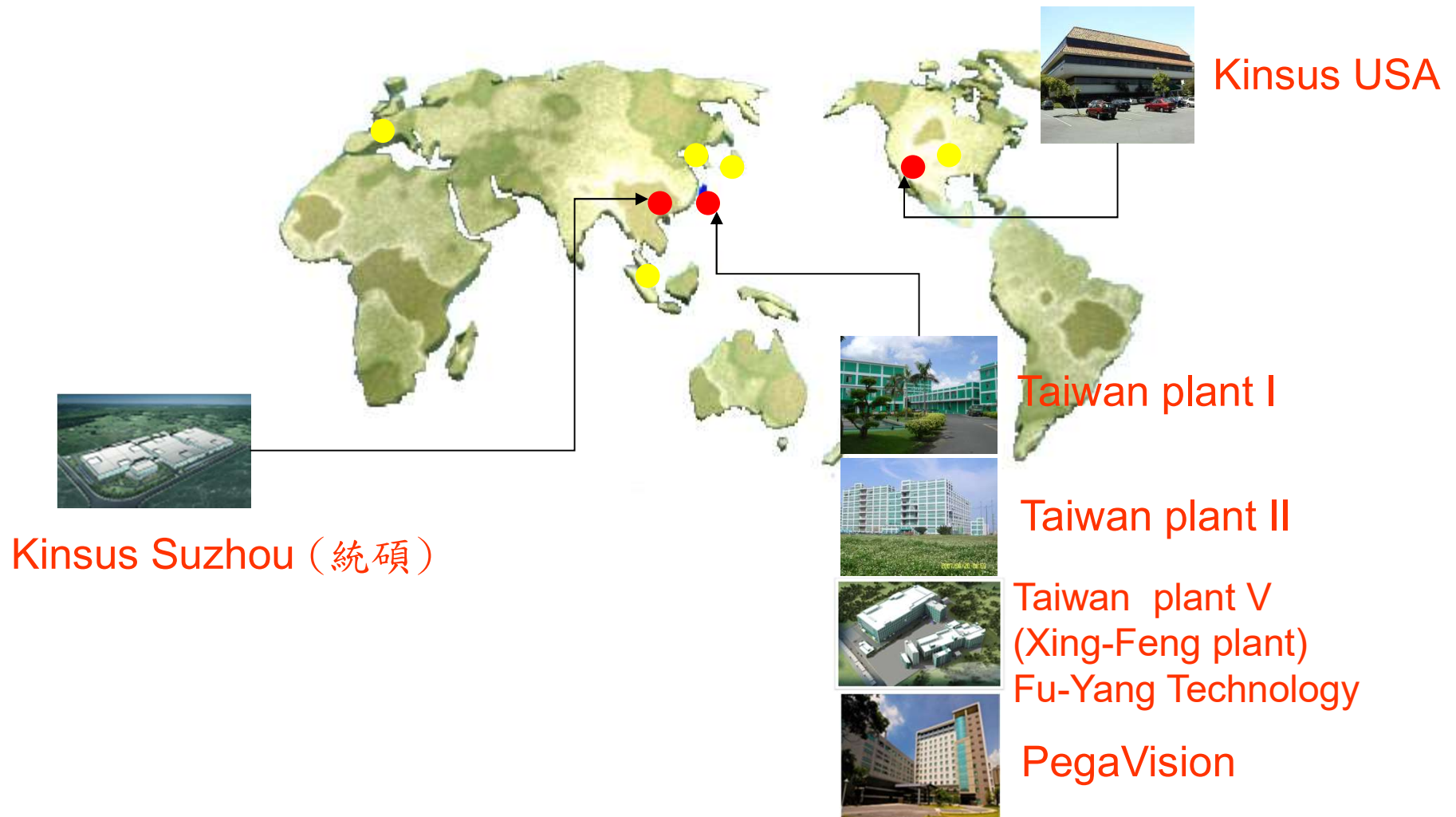


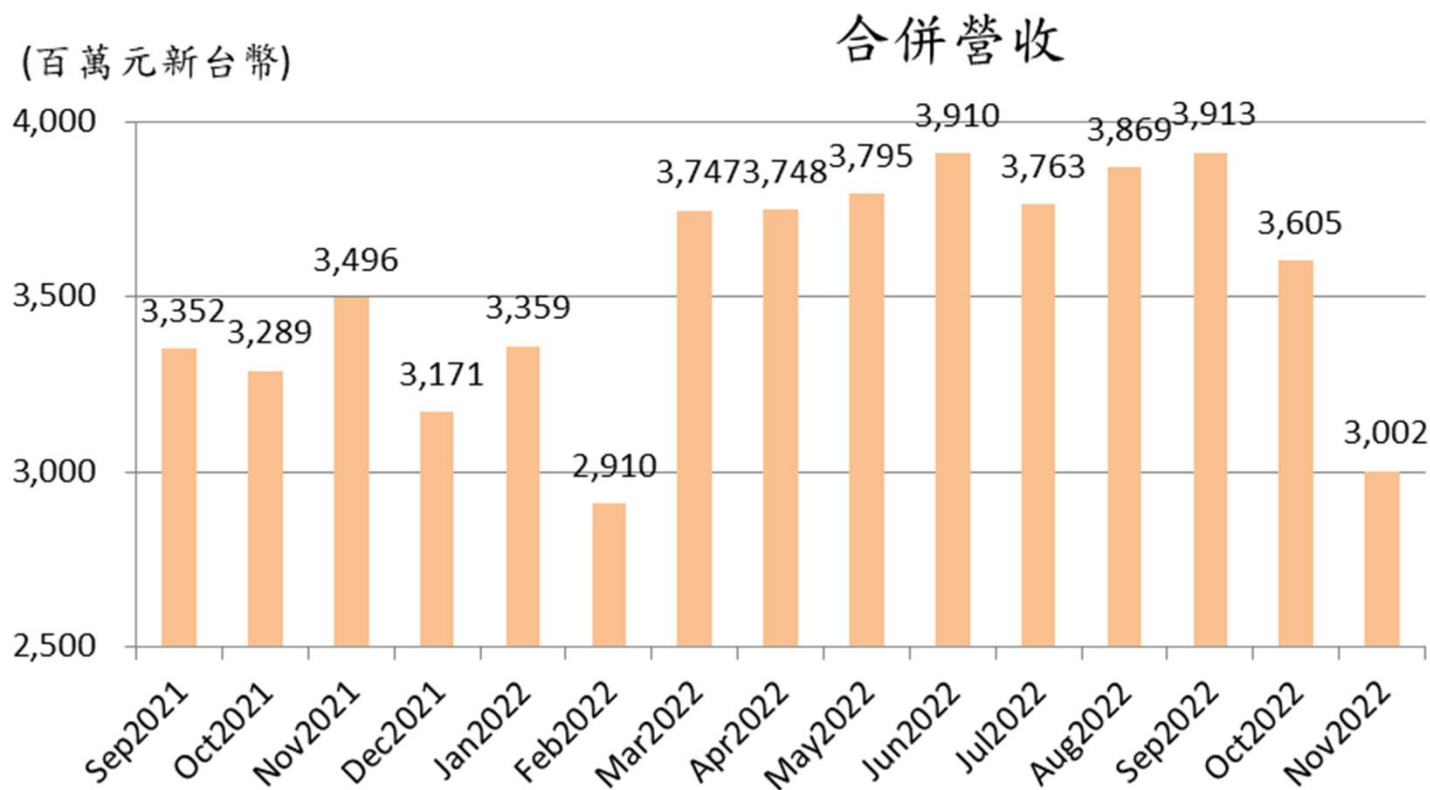
- Established in September 2000
IPO at TWSE in November 2004
- Capital : US\$ 146 Million (NT\$ 4.508 Billion)
- Campus :
 - Headquarters
 - Xin Wu / Taiwan
 - Plant I & II
 - Xing-Feng plant (Plant V)
 - IC substrates
 - Santa Clara / California
 - Suzhou / China
 - Taoyuan / Taiwan
 - Kinsus USA
 - Kinsus China
 - PegaVision

位置

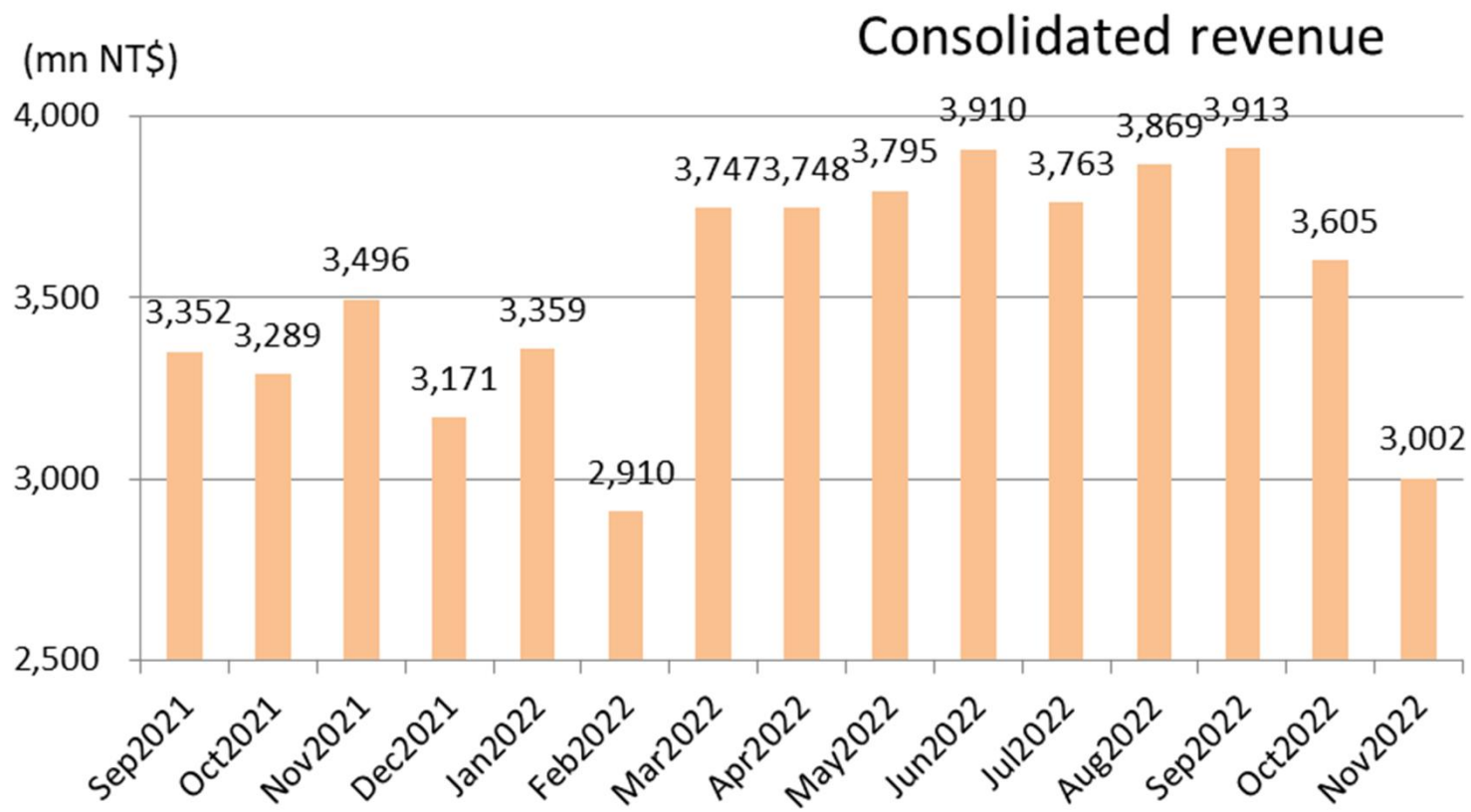


Locations

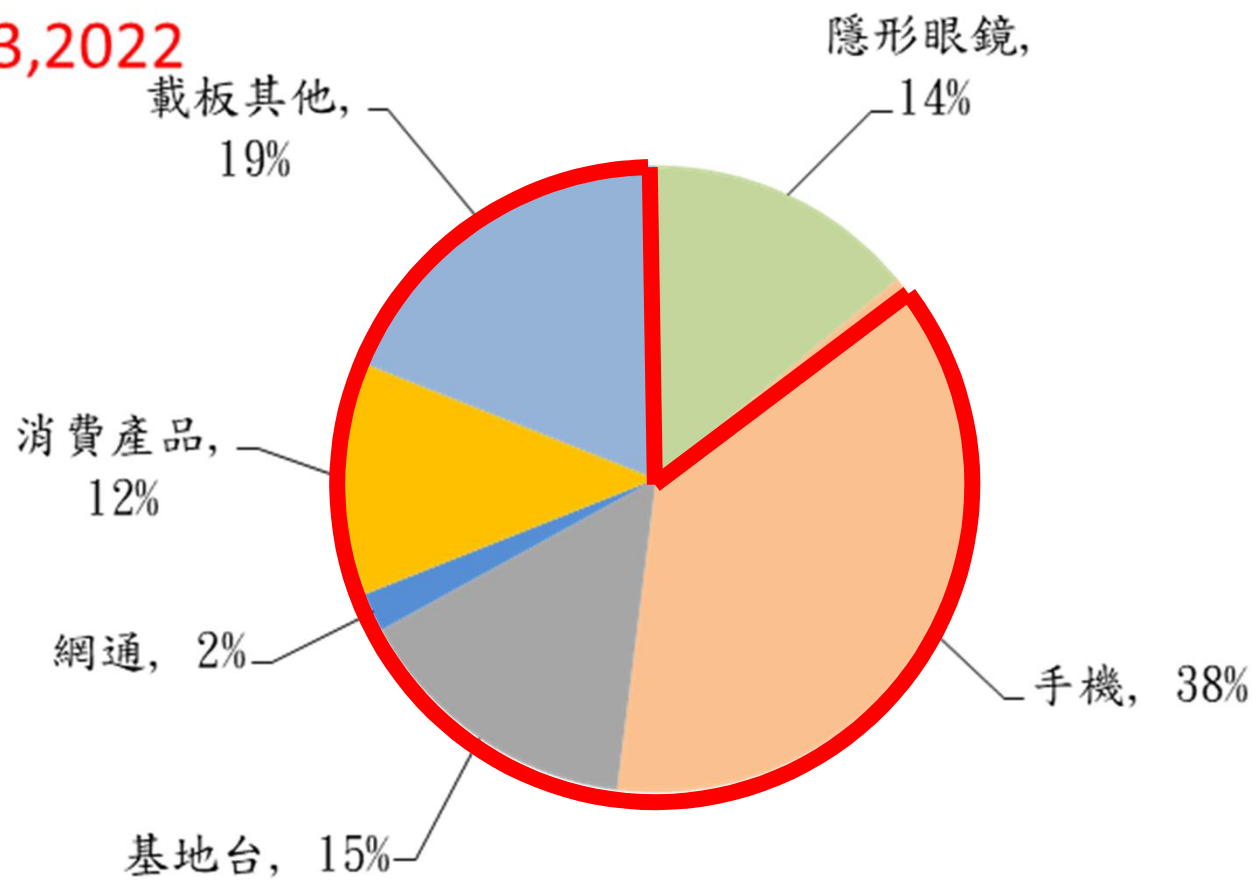




Monthly Revenue



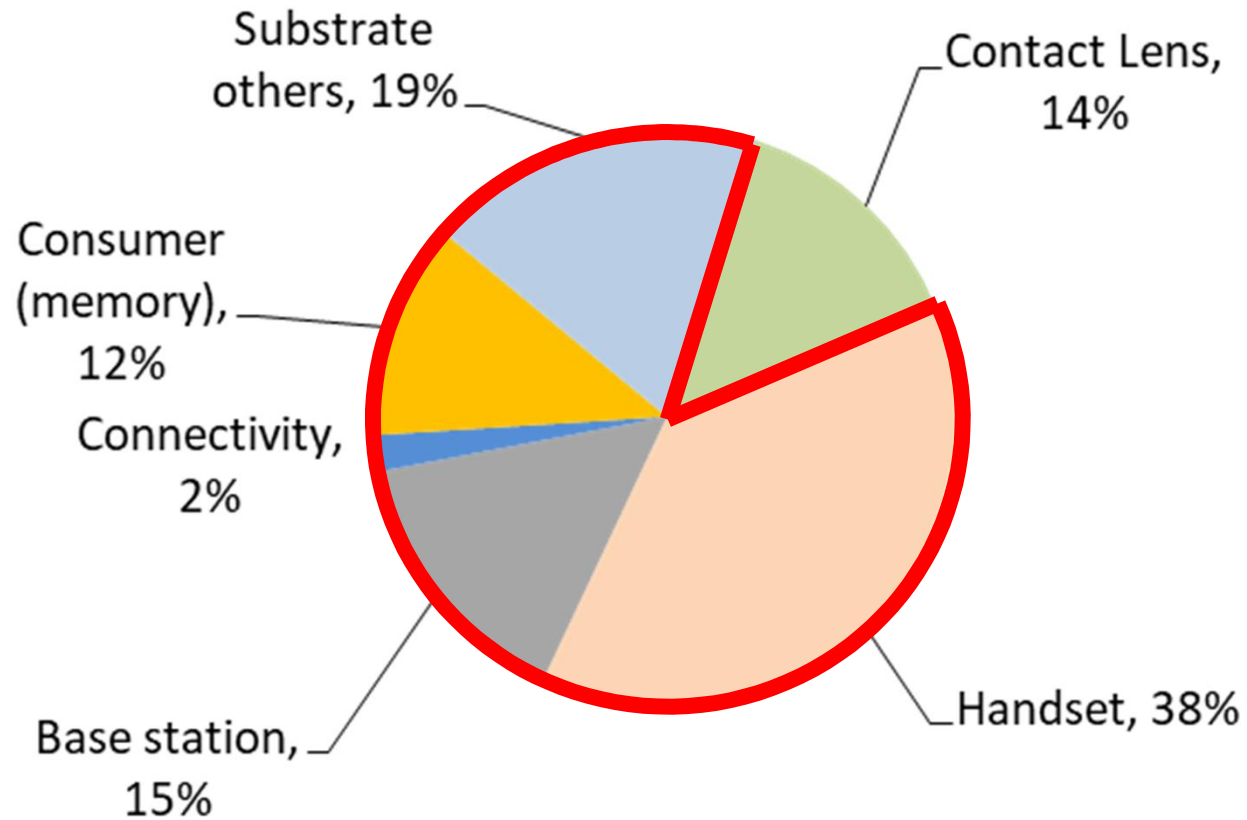
Q3, 2022



Product mix



Q3,2022





Thank you